

17611 U.S. PTO
07/14/03

DP-309697, Page 1

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Commissioner for Patents
P.O. Box 1450
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Enclosed for filing are the following patent application papers:

Docket No.: DP-309697

Inventors : SCOTT D. BRANDENBURG
DAVID A. LAUDICK

Title : WAFER APPLIED THERMALLY CONDUCTIVE INTERPOSER

16235 U.S. PTO
10/618953
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Filing Fee Formula

Basic Fee \$ 750.00

Additional Fees:

Number of independent claims in excess of 3, times \$84.00 \$ 84.00

Number of claims in excess of 20, times \$18.00 \$ 18.00

Multiple dependent claim, add \$280.00 \$ 0.00

Total Filing Fee \$ 852.00

The patent specification DP-309697 entitled WAFER APPLIED THERMALLY CONDUCTIVE INTERPOSER and filed in the Patent and Trademark Office herewith is the patent specification for which the inventor(s) executed the Declaration enclosed herewith.

Please charge the \$ 852.00 filing fee to DELPHI TECHNOLOGIES INC. Deposit Account No. 50-0831.



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Enclosures

I hereby certify that this document is being deposited with the United States Postal Service with sufficient postage as Express Mail addressed Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on July 14, 2003. Express Mail Label EV339767304 US

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